

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**Applicant(s):** William W. Feng, et al.  
**Title:** Method and system for numerically simulating foam-like material in finite element analysis  
**Serial No.:** 10/783,562  
**Confirmation No.:** 7548  
**Filing Date:** 03/19/2004  
**Examiner:** Juan Carlos Ochoa  
**Group Art Unit:** 2123  
**Docket No:** LSTC-004  
**Customer No:** 37804

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Oct. 30, 2007

Mail Stop: Issue Fee  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

## Response to Notice of Allowance

Dear Sir:

In response to the Notice of Allowance and Issue Fee Due mailed October 29, 2007, Applicant submits the following items:

1. An original copy of Issue Fee Transmittal;
2. A payment of \$720 as the issue fee.

## REMARKS

Applicant appreciates the Examiner for allowing this application. It is hereby respectfully submitted that the enclosed items complete the requirement for the issuance of the above-identified application and FIG. 6 be used for the cover sheet of the patent to be issued. Please contact the undersigned at (408)255-6853, if there are any questions.

I hereby certify that this correspondence is being transmitted to the Commissioner for Patents via the Office electronic filing system on the date stated below.

Date: Oct. 30, 2007

Signature: /Roger H. Chu, Reg. # 52745/

Roger H. Chu

Respectfully submitted,

/Roger H. Chu, Reg. # 52745/

Roger H. Chu  
Registration No. 52,745